


# MATERIAL DECLARATION SHEET



Material Number	<b>PEL12T Series</b>			
Product Line	<b>ENCODER</b>			
Compliance Date	<b>2023-12-21</b>			
RoHS Compliant	<b>YES</b>	<b>MSL</b>	<b>N/A</b>	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Shaft	PC	0.537	Polycarbonate	25971-63-5	100	18.517	18.52
2	Contact Holder	POM	0.194	Polyoxymethylene	24969-26-4	100	6.690	6.69
3	Slide Contact	t0.12 Phosphor Bronze Ag Plating (0.5~1um)	0.026	Copper	7440-50-8	91.8	0.823	0.90
				Tin	7440-31-5	8	0.072	
				Phosphine	7803-51-2	0.2	0.002	
				Silver	7440-22-4	100	0.897	
4	Leaf Spring	t0.2 Phosphor Bronze	0.124	Copper	7440-50-8	91.8	3.925	4.28
				Tin	7440-31-5	8	0.342	
				Phosphine	7803-51-2	0.2	0.009	
5	Insulation Case	PBT	0.290	Polybutylene Terephthalate	26062-94-2	69	6.900	10.00
				Glass Fiber	65997-17-3	31	3.100	
6	Terminal	t0.15 Phosphor Bronze Ag Plating (0.5~1um)	0.100	Copper	7440-50-8	91.8	3.166	3.45
				Tin	7440-31-5	8	0.276	
				Phosphine	7803-51-2	0.2	0.007	
				Silver	7440-22-4	100	3.448	

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7	LED Driving Holder Cover	PBT	0.045	Polybutylene Terephthalate	26062-94-2	69	1.071	1.55
				Glass Fiber	65997-17-3	31	0.481	
8	LED Driving Holder	HTN	0.051	HTN	25038-54-4	>99	1.741	1.76
				Additives	65997-17-3	<1	0.018	
9	LED Driving Holder Terminal	t0.1 Phosphor Bronze	0.020	Copper	7440-50-8	91.8	0.633	0.69
				Tin	7440-31-5	8	0.055	
		Phosphine		7803-51-2	0.2	0.001		
		Ag Plating (0.5~1um)		Silver	7440-22-4	100	0.690	
10	Light Emission Diode	Chip	0.012	III - V Compound	1303-00-0	0.77	0.003	0.41
		Silver paste		Silver	7440-22-4	0.67	0.003	
				Formaldehyde, polymer with 2-(chloromethyl) oxirane and 2-methylphenol	29690-82-2	0.1	0.0004	
		Gold wire		Gold	7440-57-5	0.15	0.001	
		PCB		Copper	7440-50-8	10.89	0.045	
				Nickel	7440-02-0	2.12	0.009	
				Gold	7440-57-5	0.5	0.002	
				E-glass fiber	14808-60-7	47.37	0.196	
				Epoxy resin group	25068-38-6	0.52	0.002	
				Barium sulfate	7727-43-7	0.39	0.002	
		Epoxy		Epidian	25068-38-6	21.91	0.091	
				1,3,5-Triglycidyl-s-triazinetrione	2451-62-9	4.75	0.020	
				Tetrahydrophthalic anhydride	85-43-8	9.86	0.041	

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11	Switch Contact	t0.08 Titanium with copper	0.018	Copper	7440-50-8	96.6	0.600	0.62
				Titanium	7440-32-6	3.4	0.021	
		Ag Plating (0.5~1um)						
		Silver		7440-22-4	100	0.621		
12	SW Insulation Case	PBT	0.364	Polybutylene Terephthalate	26062-94-2	69	8.661	12.55
				Glass Fiber	65997-17-3	31	3.891	
13	SW Terminal	t0.25 Brass	0.180	Copper	7440-50-8	65.685	4.077	6.20
				Iron	1345-25-1	0.035	0.002	
				Lead	7439-92-1	0.002	0.0001	
				Zinc	7440-66-6	34.278	2.128	
		Ag Plating (0.5~1um)						
				Silver	7440-22-4	100	6.207	
14	Terminal	t0.4 Steel	0.939	Iron	7439-89-6	100	32.379	32.38
		Sn Plating (5~8um)					Tin	
		<b>Total weight (g)</b>	<b>2.9</b>					

**This Document was updated on:**

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.